

ABSTRACT

SPUTTERING TARGET WITH REDUCED PARTICLE GENERATION AND METHOD
OF PRODUCING SAID TARGET

5 Provided is a sputtering target with reduced particle generation having a target surface in which intermetallic compounds, oxides, carbides, carbonitrides and other substances without ductility exist in a highly ductile matrix phase at a volume ratio of 1 to 50%, and in which the area ratio of defects on the target surface is 0.5% or less, as well as a method of producing such a sputtering target. Additionally provided are a sputtering target wherein the target surface, which contains large amounts of substances without ductility, is improved, and whereby the generation of
10 nodules and particles during sputtering can be prevented or inhibited, and a surface finishing method thereof.

Fig, 5